Complementary Darlington Power Transistor

DPAK For Surface Mount Applications

Designed for general purpose amplifier and low speed switching applications.

Features

- Lead Formed for Surface Mount Applications in Plastic Sleeves
- Surface Mount Replacements for 2N6040–2N6045 Series, TIP120–TIP122 Series, and TIP125–TIP127 Series
- Monolithic Construction With Built-in Base-Emitter Shunt Resistors
- High DC Current Gain: $h_{FE} = 2500$ (Typ) @ $I_C = 4.0$ Adc
- Epoxy Meets UL 94 V-0 @ 0.125 in
- ESD Ratings:
 - Human Body Model, 3B > 8000 V
 - ◆ Machine Model, C > 400 V
- NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant



ON Semiconductor®

www.onsemi.com

SILICON POWER TRANSISTOR 8 AMPERES 100 VOLTS, 20 WATTS



DPAK CASE 369C STYLE 1

BASE 1 EMITTER 3

MARKING DIAGRAM



A = Assembly Location

Y = Year

WW = Work Week
G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V _{CEO}	100	Vdc
Collector-Base Voltage	V _{CB}	100	Vdc
Emitter-Base Voltage	V _{EB}	5	Vdc
Collector Current Continuous Peak	lc	8 16	Adc
Base Current	IB	120	mAdc
Total Power Dissipation @ T _C = 25°C Derate above 25°C	P _D	20 0.16	W W/°C
Total Power Dissipation (Note 1) @ T _A = 25°C Derate above 25°C	P _D	1.75 0.014	W W/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-65 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	R _{0JC}	6.25	°C/W
Thermal Resistance, Junction-to-Ambient (Note1)	$R_{\theta JA}$	71.4	°C/W

These ratings are applicable when surface mounted on the minimum pad sizes recommended.

ELECTRICAL CHARACTERISTICS ($T_C = 25^{\circ}\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector-Emitter Sustaining Voltage (I _C = 30 mAdc, I _B = 0)	V _{CEO(sus)}	100	-	Vdc
Collector Cutoff Current (V _{CE} = 50 Vdc, I _B = 0)	I _{CEO}	-	10	μAdc
Collector Cutoff Current (V _{CB} = 100 Vdc, I _E = 0)	I _{CBO}	-	10	μAdc
Emitter Cutoff Current (V _{BE} = 5 Vdc, I _C = 0)	I _{EBO}	-	2	mAdc
ON CHARACTERISTICS			•	
DC Current Gain (I _C = 4 Adc, V _{CE} = 4 Vdc) (I _C = 8 Adc, V _{CE} = 4 Vdc)	h _{FE}	1000 100	12,000	-
Collector-Emitter Saturation Voltage (I _C = 4 Adc, I _B = 16 mAdc) (I _C = 8 Adc, I _B = 80 mAdc)	V _{CE(sat)}	- -	2 4	Vdc
Base-Emitter Saturation Voltage (Note 2) (I _C = 8 Adc, I _B = 80 mAdc)	V _{BE(sat)}	_	4.5	Vdc
Base-Emitter On Voltage (I _C = 4 Adc, V _{CE} = 4 Vdc)	V _{BE(on)}	_	2.8	Vdc
DYNAMIC CHARACTERISTICS				
Current-Gain-Bandwidth Product (I _C = 3 Adc, V _{CE} = 4 Vdc, f = 1 MHz)	h _{fe}	4	-	MHz
Output Capacitance (V _{CB} = 10 Vdc, I _E = 0, f = 0.1 MHz)	C _{ob}	-	200	pF
Small-Signal Current Gain (I _C = 3 Adc, V _{CE} = 4 Vdc, f = 1 kHz)	h _{fe}	300	-	-

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 2. Pulse Test: Pulse Width $\leq 300~\mu s$, Duty Cycle $\leq 2\%$.

TYPICAL CHARACTERISTICS

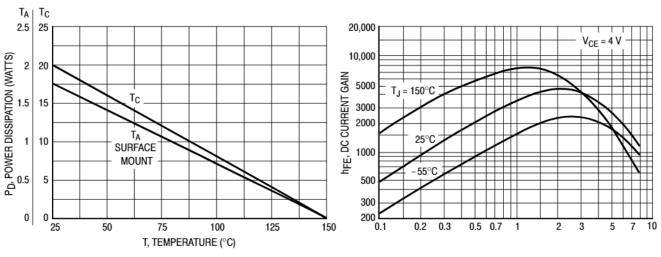


Figure 1. Power Derating

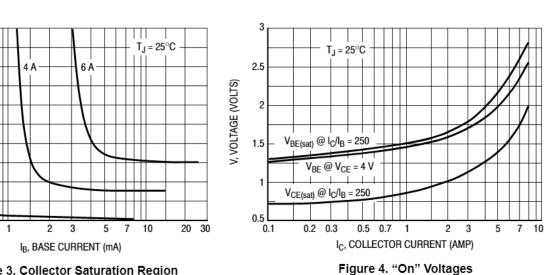


Figure 3. Collector Saturation Region

VCE, COLLECTOR-EMITTER VOLTAGE (VOLTS)

2.6

2.2

1.8

0.3

0.5 0.7

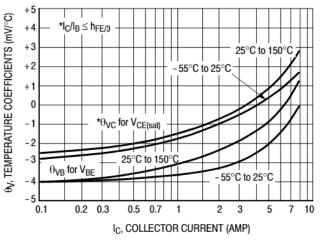


Figure 5. Temperature Coefficients

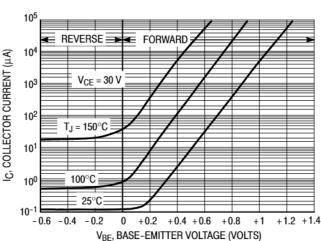


Figure 6. Collector Cut-Off Region

Figure 2. DC Current Gain

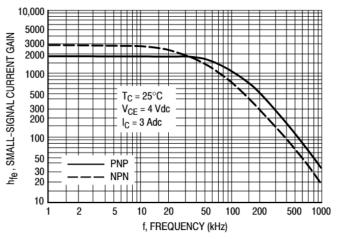


Figure 7. Small-Signal Current Gain

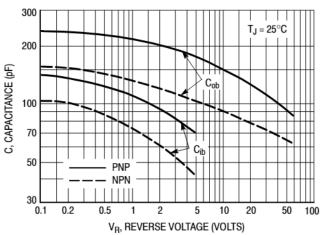


Figure 8. Capacitance

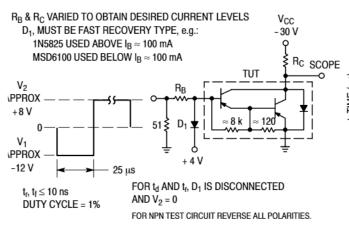


Figure 9. Switching Times Test Circuit

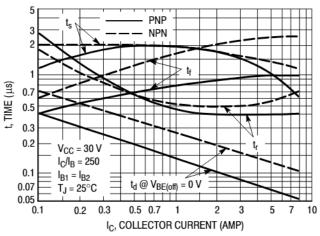


Figure 10. Switching Times

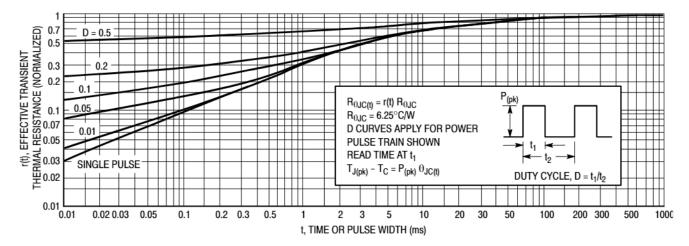


Figure 11. Thermal Response

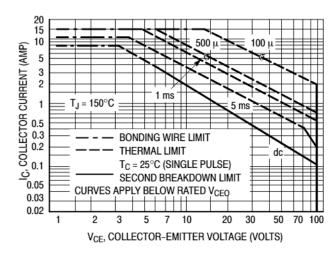


Figure 12. Maximum Forward Bias Safe Operating rea

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 12 is based on $T_{J(pk)} = 150^{\circ}\text{C}$; T_{C} is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided $T_{J(pk)} < 150^{\circ}\text{C}$. $T_{J(pk)}$ may be calculated from the data in Figure 11. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

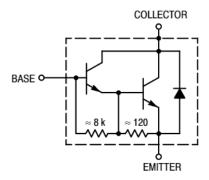


Figure 13. Darlington Schematic

ORDERING INFORMATION

Device	Package Type	Shipping [†]
NJVMJD122T4G-VF01*	DPAK (Pb-Free)	2,500 / Tape & Reel

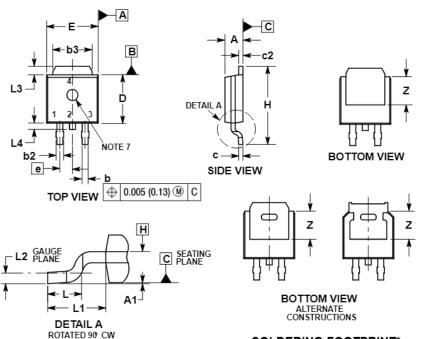
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure. BRD8011/D.

^{*}NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable

PACKAGE DIMENSIONS

DPAK (SINGLE GAUGE)

CASE 369C ISSUE F



NOTES

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M. 1994.
- T 14.3W, 1994. CONTROLLING DIMENSION: INCHES. THERMAL PAD CONTOUR OPTIONAL WITHIN DI-MENSIONS b3, L3 and Z.
- MENSIONS D., LS and Z.

 DIMENSIONS D AND E DO NOT INCLUDE MOLD

 FLASH, PROTRUSIONS, OR BURRS. MOLD

 FLASH, PROTRUSIONS, OR GATE BURRS SHALL

 NOT EXCEED 0.006 INCHES PER SIDE.

 DIMENSIONS D AND E ARE DETERMINED AT THE

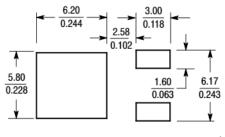
 OUTERMOST EXTREMES OF THE PLASTIC BODY.
- DATUMS A AND B ARE DETERMINED AT DATUM
 PLANE H.
- OPTIONAL MOLD FEATURE

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.028	0.045	0.72	1.14
b3	0.180	0.215	4.57	5.46
С	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
е	0.090 BSC		2.29 BSC	
Н	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.114 REF		2.90 REF	
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4		0.040		1.01
Z	0.155		3.93	

STYLE 1:

- PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR





(mm inches SCALE 3:1

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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